

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

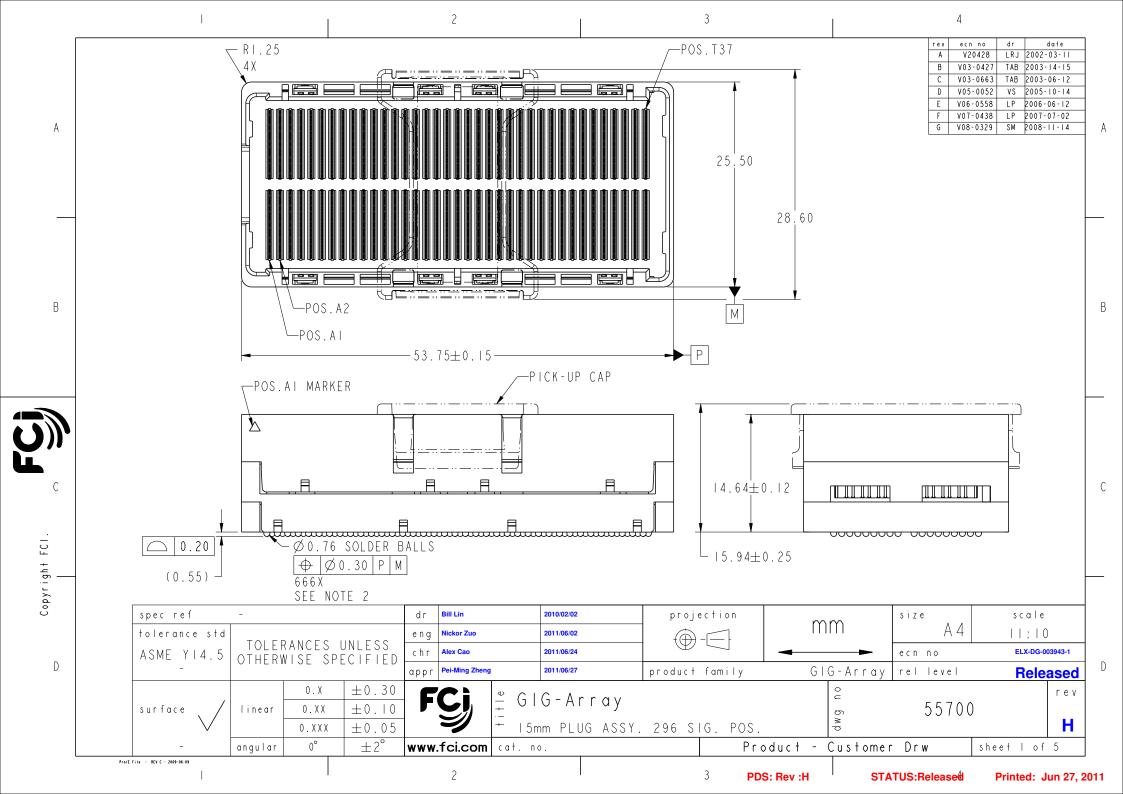
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

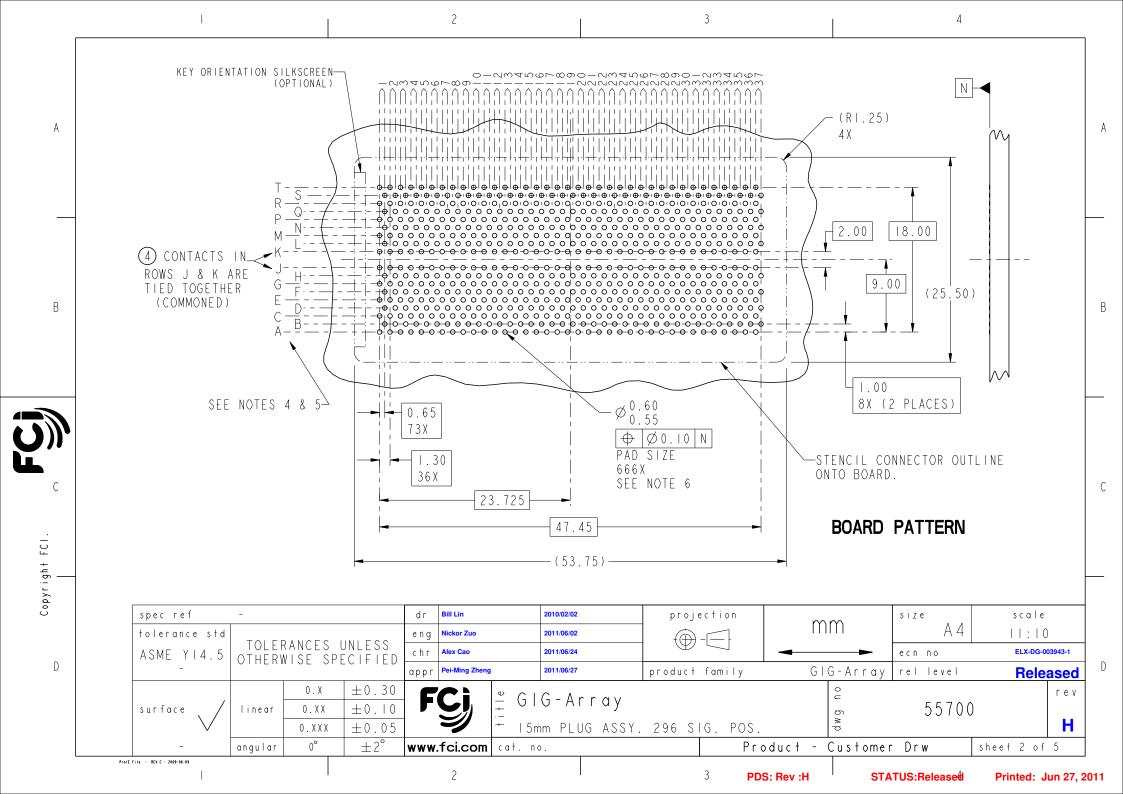
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

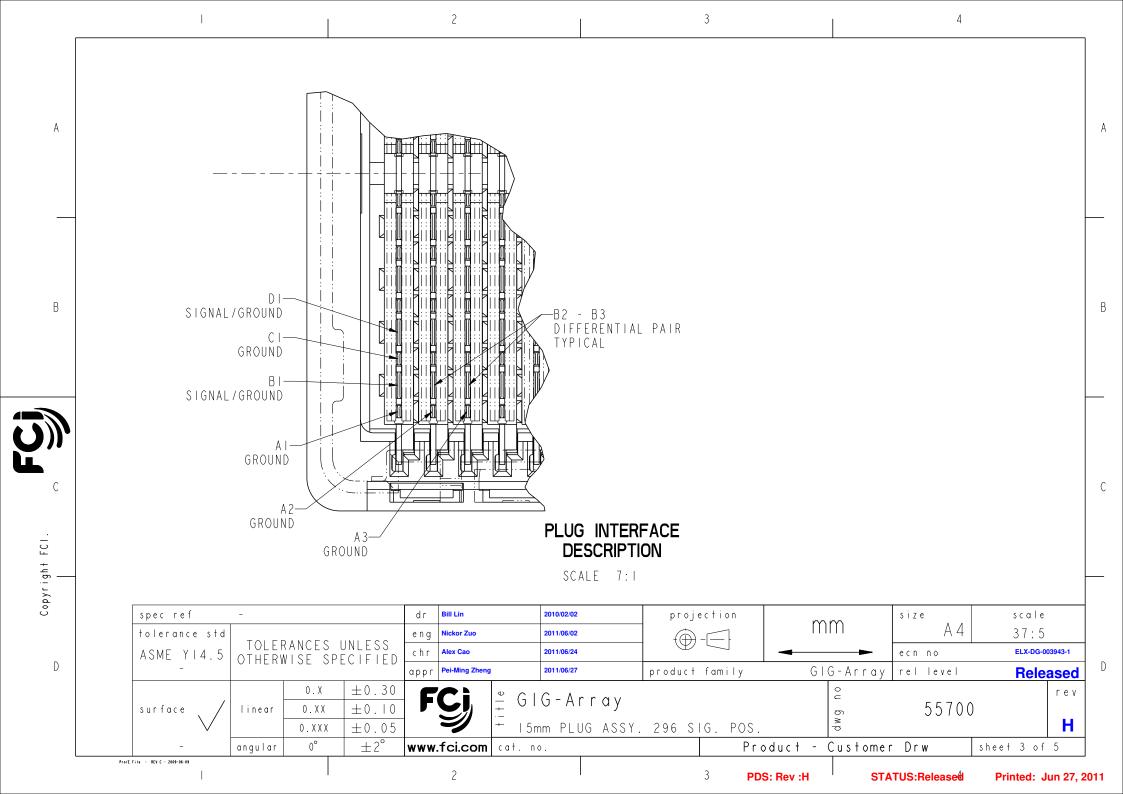


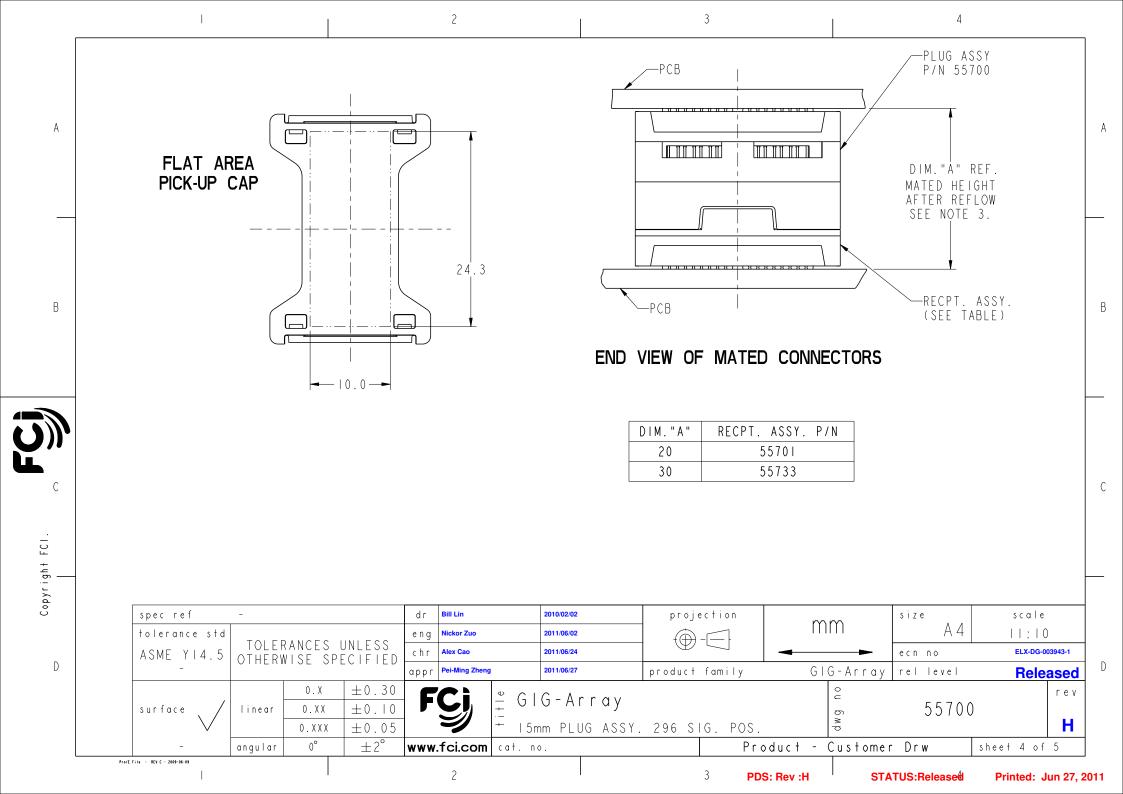












		1	2	4				
	PRODUCT NUMBER	SOLDER BALL COMPOSITION	CONTACT PLATING PERFORMANCE LEVEL					
А	55700-001	STANDARD (EUTECTIC)	PERFORMANCE-BASED PLATING, QUALIFIED TO MEET THE REQUIREMENTS OF FCI PRODUCT SPECIFICATION	N.				
	55700-001LF	LEADFREE	GS-12-192, INCLUDING TELCORDIA CENTRAL OFFICE	V				
	55700-201	STANDARD (EUTECTIC)	Au avan Ni		А			
	55700-201LF	LEADFREE	Au over Ni		А			
_		NOTES: MATERIAL: HOUSING: LCP CONTACT: COPPER ALLO PLATING (CONTACT): A UL RATING: 94 V-0	NOTES CONTINUED (6) SPECIFIED POSITIONAL TOLERANCE DEFINES PAD TO PAD LOCATION WITHIN LAND PATTERN. POSITIONAL TOLERANCE OF LAND PATTERN TO FUDICIAL MARKS OR PCB DATUMS SHALL BE DEFINED BY CUSTOMER. FOR RECOMMENDED PRODUCT APPLICATION AND PCB DESIGN DETAILS, SEE					

SOLDER BALL: (SEE TABLE) EUTECTIC SnPb OR LEADFREE 95.5 Sn/4Ag/0.5Cu

- SOLDER BALLS WILL NOT BE PERFECT SHPERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- (3) MATED HEIGHT EFFECTED BY CUSTOMERS? PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE & SOLDER PASTE.
- CONTACTS IN ROWS A,C,E,G,J,K,M,P,R AND T ARE SINGLE BEAM CONTACTS, TYPICALLY USED AS GROUND PINS. (NOTE: CONTACTS IN ROWS J & K ARE TIED TOGETHER [COMMONED])
- CONTACTS IN ROWS B, D, F, H, L, N, Q AND S ARE DUAL BEAM CONTACTS, TYPICALLY USED AS SIGNAL PINS.

- DOC. NO. GS-20-016.
- 7) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEADFREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEADFREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.
- (8)THIS PRODUCT MEETS THE EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. PRODUCT MEETING WITH THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.

spec ref	ecref -		dr	dr Bill Lin		2010/02/02	projection ———	ction	100 100		s i z e	scale			
tolerance std	T 0 . F 5				Nickor Zuo			2011/06/02	mm		A 4	11:10			
ASME YI4.5	I OLEH Lothern	TOLERANCES UNLESS THERWISE SPECIFIED		chr	Alex Cao		2011/06/24			→		ecn no	ELX-DG-0	ELX-DG-003943-1	
-	OTHERWISE STECTIFED			appr Pei-Ming Zheng		2011/06/27	product family		G	IG-Array	rel level	Rele	Released		
		0.X	±0.30			≟ GIG-Array					0 0			rev	
surface /	linear	0.XX	±0.10							<u>ත</u>	55700)			
		0.XXX ±0	±0.05			nm PLUG ASSY.	296 SIG. POS.			× ⊘			Н		
-	angular	0°	±2°	www.	fci.com	cat, no).		Pro	duct -	Customer	Drw	sheet 5 of	5	

Pro/E File - REV C - 2009-06-09

PDS: Rev:H

STATUS:Released

Printed: Jun 27, 2011

В

()